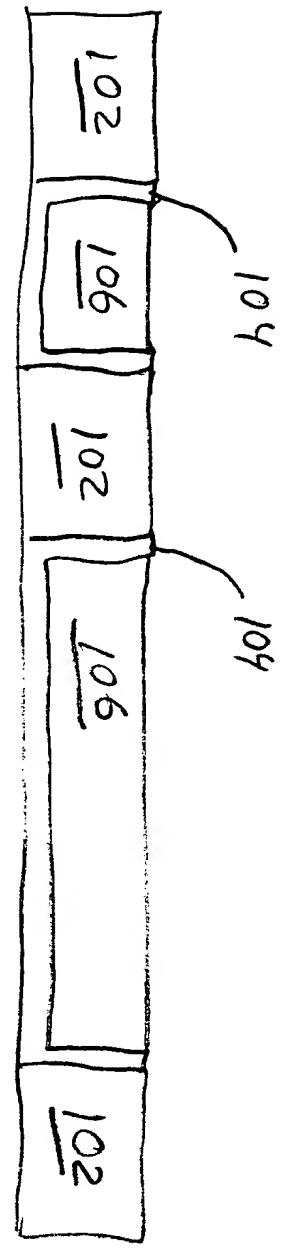


Fig. 1

P0138

P8136

Fig. 2



302

Provide a slurry having an abrasive harder than a first layer and less hard than an underlying second layer to polishing pad

304

Bring substrate with first layer thereon into contact with polishing pad

306

Polish first layer

308

Stop polish on second layer

Fig. 3